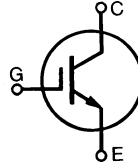


HiPerFAST™ IGBT

IXGA 15N120B
IXGP 15N120B

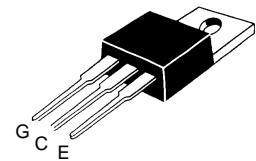
V_{CES} = 1200 V
I_{C25} = 30 A
V_{CE(sat)} = 3.2 V
t_{fi(typ)} = 160 ns



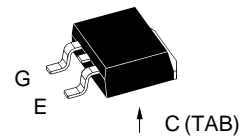
Preliminary data

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T _J = 25°C to 150°C	1200	V
V_{CGR}	T _J = 25°C to 150°C; R _{GE} = 1 MΩ	1200	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T _C = 25°C	30	A
I_{C90}	T _C = 90°C	15	A
I_{CM}	T _C = 25°C, 1 ms	60	A
SSOA (RBSOA)	V _{GE} = 15 V, T _{VJ} = 125°C, R _G = 10 Ω Clamped inductive load	I _{CM} = 40 @ 0.8 V _{CES}	A
P_C	T _C = 25°C	150	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C
M_d	Mounting torque with screw M3 Mounting torque with screw M3.5	0.45/4 0.55/5	Nm/lb.in.
Weight	TO-220 TO-263	4 2	g

TO-220AB (IXGP)



TO-263 AA (IXGA)



Features

- International standard packages JEDEC TO-220AB and TO-263AA
- Low switching losses, low V_{CE(sat)}
- MOS Gate turn-on - drive simplicity

Applications

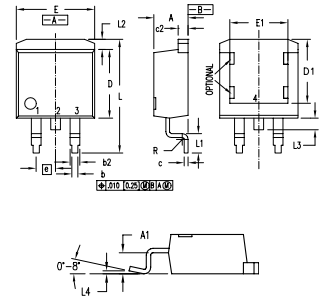
- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

Advantages

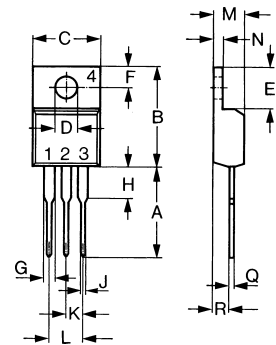
- Easy to mount with one screw
- Reduces assembly time and cost
- High power density

Symbol	Test Conditions (T _J = 25°C, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	I _C = 250 μA, V _{GE} = 0 V	1200		V
V_{GE(th)}	I _C = 250 μA, V _{CE} = V _{GE}	2.5		V
I_{CES}	V _{CE} = V _{CES} , T _J = 25°C			100 μA
	V _{GE} = 0 V, T _J = 125°C			3.5 mA
I_{GES}	V _{CE} = 0 V, V _{GE} = ±20 V			±100 nA
V_{CE(sat)}	I _C = I _{CE90} , V _{GE} = 15			3.2 V
	T _J = 125°C		2.5	V

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values			
		Min.	Typ.	Max.	
g_{fs}	$I_C = I_{C90}$; $V_{CE} = 10\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$	12	15	S	
C_{ies}	$V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 1\text{ MHz}$		1720	pF	
C_{oes}			95	pF	
C_{res}			35	pF	
Q_g	$I_C = I_{C90}$; $V_{GE} = 15\text{ V}$, $V_{CE} = 0.5 V_{CES}$		69	nC	
Q_{ge}			13	nC	
Q_{gc}			26	nC	
$t_{d(on)}$	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15\text{ V}$ $V_{CE} = 960\text{ V}$, $R_G = R_{off} = 10\ \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 V_{CES}$, higher T_J or increased R_G		25	ns	
t_{ri}			15	ns	
$t_{d(off)}$			180	280	ns
t_{fi}			160	320	ns
E_{off}			1.75	3.0	mJ
$t_{d(on)}$	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15\text{ V}$ $V_{CE} = 960\text{ V}$, $R_G = R_{off} = 10\ \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 V_{CES}$, higher T_J or increased R_G		25	ns	
t_{ri}			18	ns	
E_{on}			0.60	mJ	
$t_{d(off)}$			300	ns	
t_{fi}			360	ns	
E_{off}		3.5	mJ		
R_{thJC}	TO-220		0.83	K/W	
R_{thCK}			0.5	K/W	

TO-263 AA (IXGA) Outline


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.06	4.83	.160	.190
A1	2.03	2.79	.080	.110
b	0.51	0.99	.020	.039
b2	1.14	1.40	.045	.055
c	0.46	0.74	.018	.029
c2	1.14	1.40	.045	.055
D	8.64	9.65	.340	.380
D1	7.11	8.13	.280	.320
E	9.65	10.29	.380	.405
E1	6.86	8.13	.270	.320
e	2.54	BSC	.100	BSC
L	14.61	15.88	.575	.625
L1	2.29	2.79	.090	.110
L2	1.02	1.40	.040	.055
L3	1.27	1.78	.050	.070
L4	0	0.38	0	.015
R	0.46	0.74	.018	.029

TO-220 AB (IXGP) Outline


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	12.70	13.97	0.500	0.550
B	14.73	16.00	0.580	0.630
C	9.91	10.66	0.390	0.420
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.230	0.270
F	2.54	3.18	0.100	0.125
G	1.15	1.65	0.045	0.065
H	2.79	5.84	0.110	0.230
J	0.64	1.01	0.025	0.040
K	2.54	BSC	0.100	BSC
M	4.32	4.82	0.170	0.190
N	1.14	1.39	0.045	0.055
Q	0.35	0.56	0.014	0.022
R	2.29	2.79	0.090	0.110

Min. Recommended Footprint
